

**In the Claims:**

Please amend the Claims as follows:

Claim 1. (Currently Amended) A method Method to produce electronic components with closely adjacent electrodes on a substrate such that characterized in that the structuring of the electrodes is achieved using the following steps:

- a) structuring a photo lacquer is structured on a the substrate with overlapping edges;
- b) depositing a metal vapor is deposited onto the substrate and the structured photo lacquer;
- c) applying an insulator is applied over the deposited metal vapor, structured photo lacquer, and substrate surface thus produced;
- d) etching the insulator is etched, whereby such that flat edges are formed on the overlapping edges of the photo lacquer as an inverse of the overlaps.

Claim 2. (Currently Amended) A method Method to produce electronic components with closely adjacent electrodes on a substrate such that characterized in that the structuring of the electrodes is achieved using the following steps:

- a) depositing a metal layer is deposited onto the substrate;
- b) structuring a photo lacquer is structured on the metal layer;
- c) etching the exposed metal layer is etched, whereby such that overhangs arise are formed in the photo lacquer by means of controlled undercutting of the metal;
- d) exposing the The surface thus produced is exposed to metal vapor;
- e) removing the photo lacquer with its metal layer is removed.

Claim 3. (Currently Amended) The method of claim 2 Method to produce electronic components with closely adjacent electrodes on a transparent substrate characterized in that further comprising:

- a) The electrodes are structured on the substrate as in Claim 2;
- ba) depositing a A transparent organic semi-conductor and a transparent insulator are deposited on the surface thus produced,
- eb) depositing a A second photo lacquer is deposited on an the upper side, and performing photo lithography is performed on an the underside,
- dc) depositing a metal vapor is deposited onto the surface thus produced,

- ed) removing the remaining photo lacquer with its metal layer ~~is removed,~~
- fe) the electronic component is completed by etching the at least one contact contact[s] until they are it is exposed.

Claim 4. (Currently Amended) The method of claim 2 further comprising Method to produce electronic components with closely adjacent electrodes on a substrate characterized in that:

- a) ~~The electrodes are structured on the substrate as in Claim 2;~~
- ba) etching holes Holes or grooves are etched into the substrate at those positions without metal,
- eb) depositing a A second thin metal layer is deposited,
- dc) applying an An insulator is applied,
- ed) etching the The insulator on an the upper side of the substrate is etched;
- fe) applying an An organic semi-conductor is applied and sealing the surface is sealed,
- gf) exposing at least one The buried gate[s] are exposed gate using a photolithographic process.